

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L21	513	(trim\$4 or cut\$4 or dip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated and (table or (Look table)) and ((select\$3 or choosi\$3 or determini\$3) with (recipe or process)) AND (WAFER OR SEMI CONDUCTOR OR WORKPIECE OR DIE OR ic OR (INTEGRATED CIRCUIT))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/04 09:59
S1	17685	(TOKYO same ELECTRON). as.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/24 09:19
S2	3449	((TOMOYASU same MASAYUKI) or (FUNK MERRITT LANE) or (PINTO KEVIN AUGUSTINE) or (ODAGIRI MASAYA) or (CHEN LEMUEL) or (YAMASHITA ASAO) or (IWAMI AKIRA) or (TAKAHASHI HIROYUKI)).in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 09:22
S4	1	"20040185583"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 11:53
S5	8	10/229,446	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 14:08
S6	2	"20030045131"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 14:10
S7	0	METHODS AND APPARATUS FOR PROCESSING MICROELECTRONIC WORKPIECES USING METROLOGY	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 14:12
S8	2	(METHODS APPARATUS PROCESSING MICROELECTRONIC WORKPIECES USING METROLOGY).ti.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 14:12
S9	7	60/454,597	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 14:14

S10	6	("10705201" or "10705200" or "10704969" or "10705397")	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/24 15:38
S11	161	(TOKYO same ELECTRON). as. and metrology.dlm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/24 16:22
S12	30	("4659220" "4869593" "4899055" "5042949" "5191393" "5258823" "5291269" "5486701" "5517032" "5604344" "5616063" "5695601" "5747813" "5757502" "5825498" "5835225" "5872633" "5943122" "5948203" "5957749" "6052188" "6108091" "6108092" "6111634" "6120348" "6142855" "6157450" "6184984" "6406641" "6413867").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/24 16:29
S13	1132033	WO "03021642"	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/24 16:32
S17	74	verbeke.in.	US-PGPUB; USPAT; USOCR	ADJ	OFF	2009/09/24 16:32
S18	16	verbeke.in. and WO	US-PGPUB; USPAT; USOCR	ADJ	OFF	2009/09/24 16:32
S19	113	verbeke.in.	US-PGPUB; USPAT; USOCR; EPO	ADJ	OFF	2009/09/24 16:34
S21	2	(WO "3021642") or (WO "204887") or (WO "2004084280")	US-PGPUB; USPAT; USOCR; EPO	ADJ	OFF	2009/09/24 16:36
S22	1	(WO "3021642") or (WO "204887") or (WO "4084280")	US-PGPUB; USPAT; USOCR; EPO	ADJ	OFF	2009/09/24 16:36
S23	2	(WO "3021642") or (WO "0204887") or (WO "2004084280")	US-PGPUB; USPAT; USOCR; EPO	ADJ	OFF	2009/09/24 16:36
S24	2	(WO "3021642") or (WO "204887") or (WO "2004084280")	US-PGPUB; USPAT; USOCR; EPO	ADJ	OFF	2009/09/24 16:38
S25	3	("6165805" "6438441" "5240556").pn.	US-PGPUB; USPAT; USOCR; EPO	ADJ	OFF	2009/09/24 16:48
S26	949	(TOKYO same ELECTRON). as. and (metrology or measur \$3).dlm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/24 17:23

S27	7	"6960416"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/24 18:22
S28	245	(control and (strategy and plan) and recipe) and semiconductor	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/25 16:53
S29	1	oxidized Tunable Etch Resistant ARC (TERA)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/25 17:09
S30	2543	oxidized Tunable Etch Resistant ARC or (TERA)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/25 17:09
S31	2543	(oxidized Tunable Etch Resistant ARC) or (TERA)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/25 17:09
S32	1	(oxidized Tunable Etch Resistant ARC)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/25 17:09
S34	59	(Tunable Etch Resistant ARC) or (tera material)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/25 17:11
S35	315	wall heating (element or lamp or apparatus)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/28 16:44
S36	12	wall heating (element or lamp or apparatus) and wafer	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/28 16:51
S37	5506	(TOKYO same ELECTRON). as. and pressure	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 07:53
S38	876	(TOKYO same ELECTRON). as. and (low adj pressure)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 07:53
S39	112	(TOKYO same ELECTRON). as. and (low adj pressure with ("10" or "100" or "75"))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 07:54
S40	49	(TOKYO same ELECTRON). as. and (low adj pressure with ("10" or "100" or "75")) and mtorr	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 07:55
S42	32365	(low adj pressure) with process\$3	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 08:00
S43	42	(TOKYO same ELECTRON). as. and (low adj pressure with ("10" or "100" or "75")) and mtorr and temperature	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 08:01
S44	23	(TOKYO same ELECTRON). as. and (low adj pressure with ("10" or "100" or "75")) and mtorr and (temperature with gas)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 09:37

S45	53295	temperature process gas	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2009/09/29 09:44
S46	1213	(TOKYO same ELECTRON). as. and S45	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 09:44
S50	231	(TOKYO same ELECTRON). as. and S45 and (distribution system)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2009/09/29 09:45
S51	75	(thermal treatment chamber) and (temperature with ("10" or "50"))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 09:58
S52	4	US-6284086-\$.D.ID. OR US- 4838978-\$.D.ID. OR WO- 0178517-\$.D.ID. OR US- 4492618-\$.D.ID. OR US- 5273588-\$.D.ID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 10:40
S53	3	US-6284006-\$.D.ID. OR US- 4838978-\$.D.ID. OR WO- 0178517-\$.D.ID. OR US- 4492610-\$.D.ID. OR US- 5273588-\$.D.ID. OR 2002/195201 OR 2002/802947 OR US- 5273588-\$.D.ID. OR 2002/811216	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 10:47
S54	125	"6284006" OR "4838978" OR WO-0178517 OR "4492610" OR "5273588" OR 2002/195201 OR 2002/802947 OR "5273588" OR WO-2002/811216	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 10:49
S55	125	"6284006" OR "4838978" OR (WO-0178517) OR "4492610" OR "5273588" OR 2002/195201 OR 2002/802947 OR "5273588" OR (WO-2002/811216)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 10:49
S56	4	("6284006" OR "4838978" OR (WO-0178517) OR "4492610" OR "5273588" OR 2002/195201 OR 2002/802947 OR "5273588" OR (WO-2002/811216)).pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 10:50
S57	55	(thermal treatment chamber) and (low with temperature)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 10:55
S58	22	"5240556"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 11:02
S59	347	((Ishikawa Yoshio) or (arami Junichi) or (Ikeda Towli) or (Iwata Teruo)).in.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 11:06

S60	3038366	temperature	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 11:06
S61	95	S59 and S60	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 11:07
S62	1	"5484483".pn.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 11:16
S63	53	"5221403"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 11:21
S64	53	"5,221,403"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 11:44
S65	0	eric strang	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 13:24
S66	120	(eric same strang).in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 13:24
S67	2	"20030045131" and (temperature and gas)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 14:35
S68	1769	gas distribution system and temperature	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 14:46
S69	1481	gas distribution system and temperature and (wafer or chamber or semiconductor)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 14:50
S70	521	((gas distribution system) same temperature) and (wafer or chamber or semiconductor)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 14:58
S71	726	((thermal treatment chamber) or (process space same chamber) and (temperature)) and (wafer or substrate or workpiece or (work piece))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 16:03
S72	726	((thermal treatment chamber) or (process space same chamber) and (temperature)) and (wafer or substrate or workpiece or (work piece))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 16:03
S73	3	US-4898798-\$.DID. OR US- 5303671-\$.DID. OR US- 5254505-\$.DID. OR US- 438785D-\$.DID.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 16:24

S74	5	US-6544380-\$.DID. OR US-5634551-\$.DID. OR US-6616767-\$.DID. OR US-1912152-\$.DID. OR US-6515261-\$.DID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 16:29
S75	72	thermal treatment chamber with temperature	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 16:44
S76	1	"20040185583".pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 17:08
S77	10	US-6884734-\$.DID. OR US-6926843-\$.DID. OR US-20040191998-\$.DID. OR US-4381300-\$.DID. OR US-20050218113-\$.DID. OR US-20050227494-\$.DID. OR US-20040097047-\$.DID. OR US-20040185583-\$.DID. OR US-122004D-\$.DID. OR US-20040110354-\$.DID. OR US-5282925-\$.DID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 17:11
S78	8021	trim\$4 with amount	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 17:18
S79	0	determin43 same trim\$4 with amount	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 17:18
S80	997	determin\$3 same trim\$4 with amount	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 17:19
S81	367	determin\$3 same trim\$4 with amount and (wafer or substrate or workpiece or (work piece) or semiconductor)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2009/09/29 17:19
S82	2	"20030045131"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2009/09/29 18:01
S83	5	US-5769952-\$.DID. OR US-5368054-\$.DID. OR US-6745637-\$.DID. OR US-6267122-\$.DID. OR US-20010024691-\$.DID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/29 18:58
S84	3	US-5672239-\$.DID. OR US-5776360-\$.DID. OR US-6467491-\$.DID. OR EP-0998170-\$.DID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/29 19:01
S85	206	((applied materials).as. and (((lookup or (look adj up)) adj table) or (bin with table) or (bin with algorithm))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 08:10

S86	98	((applied materials).as. and ((bin\$4 with table) or (bin\$4 with algorithm) or (bin\$4 with method))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 08:28
S87	2	"4345312".pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 08:43
S88	208	((applied materials).as. and (((lookup or (look adj up)) adj table) or (bin with table) or (bin\$4 with algorithm))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 08:47
S89	30744	((wafer or semiconductor) and ((bin\$4 with table) or (bin\$4 with algorithm) or (bin \$4 with method))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 08:56
S90	2493	((wafer or semiconductor) and ((bin\$4 with table) or (bin\$4 with algorithm) or (bin \$4 with method)) and (trim \$4)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 08:56
S91	191	((wafer or semiconductor) and ((bin\$4 with table) or (bin\$4 with algorithm) or (bin \$4 with method)) and (trim \$4 with value)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 09:08
S92	2408	((700/121).ccls.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 10:38
S93	1	"20020175384"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2009/09/30 10:52
S94	2	"20030045131"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/12 17:08
S95	61	((TERA adj (layer or material or film))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 09:06
S96	2	"20030045131"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 09:08
S98	20	((TOKYO same ELECTRON). as. and (TERA adj material)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 09:14
S99	2	"7042564"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 10:07
S100	1	"20040071888"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 13:10
S101	1	"10812354"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 13:14

S102	0	60/4544597	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 13:29
S103	7	60/454,597	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 13:29
S104	83	(TOKYO same ELECTRON). as. and (isolated and nested)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 14:15
S105	51	(TOKYO same ELECTRON). as. and (isolated and nested and target)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 14:15
S106	48	(TOKYO same ELECTRON). as. and (isolated and nested and target and compar\$3)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 14:53
S108	1	(TOKYO same ELECTRON). as. and (bin\$4 adj (table or algorithm))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/13 14:56
S109	3	(TOKYO same ELECTRON). as. and (control recipe selection)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/04/13 14:57
S110	21	(TOKYO same ELECTRON). as. and (control recipe selection)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:11
S111	52	(TOKYO same ELECTRON). as. and (control recipe selecti \$3)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:11
S112	247	(control recipe selecti\$3)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:15
S113	117	(control recipe selecti\$3 and (target or desired))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:19
S114	26	09/637,620,	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:36
S115	0	(applied material).as. and (user interface) and (target or desired)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:48
S116	2	(applied material).as. and (user interface) and (target or desired)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:48
S117	2	(applied material).as. and (user interface) and (target or desired)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:48
S118	2	(applied material).as. and (user interface) and (target or desired or setpoint)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:50
S119	6	(applied material).as. and (interface) and (target or desired or setpoint)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/13 15:50

S120	303405	waits	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	ON	2010/04/13 16:00
S121	4	"6903023"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	ON	2010/04/13 17:35
S122	2	("626167" "6514667").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	ON	2010/04/13 17:52
S123	31	(TOKYO same ELECTRON). as. and (creat\$3 with (bin\$4 or bin or (control recipe select\$3))) and bin\$4	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/14 10:58
S124	1375658	tel R2R controller	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/04/14 11:05
S125	0	tel R2R controller	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/04/14 11:05
S126	2	tel R2R controller	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/14 11:05
S127	84	R2R controller	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/14 11:05
S128	2	"7337019"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/14 11:14
S129	74	"5354715"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/14 11:40
S130	0	"0040071888"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/14 12:01
S131	1	"20040071888"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/04/14 12:01
S132	5	US-20020011210-\$.D.ID. OR US-4960488-\$.D.ID. OR US- 5824375-\$.D.ID. OR US- 6042887-\$.D.ID. OR US- 6846745-\$.D.ID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/04/14 12:52

S133	30	("20010031506" "20020192966" "20030014145" "20030228532" "20030230551" "20040038139" "20040185583" "20040267399" "20050218113" "20050227494" "5926690" "5946079" "6297166" "6511898" "6587744" "6665575" "6665623" "6732007" "6884734" "6893975").PN. OR ("7209798" "7292906"). URPN.	US-PGRUB; USPAT; USOCR	OR	OFF	2010/04/14 13:03
S134	0	("2006/0195218").URPN.	USPAT	OR	OFF	2010/04/14 13:10
S135	0	("2006/0195218").URPN.	USPAT	OR	OFF	2010/04/14 13:11
S136	5	"6,864,041"	USPAT	OR	OFF	2010/04/14 13:13
S137	5	"6864041"	USPAT	OR	OFF	2010/04/14 14:02
S138	1	"12214918"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/10/25 11:48
S139	1	("6087238").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 11:04
S140	9	("6087238" "6165805" "6438441" "6245581" "20030003607" "6461878" "6395094" "5943550" "6841584").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 11:10
S141	3	"11046903"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 11:21
S142	1	US-6864041-\$.DID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 11:28
S143	2	"10944463"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 11:30
S145	3	("20030045131" "7337019" "7042564").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 12:01
S146	118	(semtool).as. and processing microelectronic	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/02 13:33

S147	4	(semitool).as. and processing microelectronic with metrology	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/02 13:33
S148	29	"5240556"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/02 13:50
S149	1	"20040262254"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/02 14:16
S150	3	("2003235211" "2007078525").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 17:41
S151	3	("20030235211" "2007078525").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 17:42
S152	2	("20030235211" "20070078525").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 17:42
S153	3	US-20070078525-\$.D.ID. OR US-20050159932-\$.D.ID. OR US-20030235211-\$.D.ID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 17:46
S154	1	"12217581"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/02 18:05
S155	258	(TOKYO same ELECTRON). as. and (bin\$4)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/03 09:36
S156	121	(TOKYO same ELECTRON). as. and (control recipe select \$3)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 09:42
S157	86	(TOKYO same ELECTRON). as. and (control recipe select \$3) and table	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 09:42
S158	22	multi-dimensional recipes	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 09:49
S159	1	"20060079983"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 10:00
S160	2	("20050233477" "20030052083").pn.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 10:07
S161	13	(TL with ingenio)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 10:10
S162	2	"60414,425"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 10:16

S163	9	US-20040135590-\$.DID. OR US-20030208294-\$.DID. OR US-20030169330-\$.DID. OR US-20030061537-\$.DID. OR US-6842660-\$.DID. OR US- 6819963-\$.DID. OR US- 6630362-\$.DID. OR US- 6571285-\$.DID. OR US- 6480854-\$.DID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 10:44
S164	0	(applied material).as. and nested	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 11:15
S165	170	(applied materials).as. and nested	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	WITH	OFF	2010/11/03 11:15
S166	170	(applied materials).as. and nested	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 11:15
S167	4	(applied materials).as. and (nested data)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 11:16
S168	338	(nested same isolated) same data	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 11:18
S169	107	(nested same isolated) same data and etch\$3	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 11:18
S170	1040	(iso\$7 same nested) same (data or information or value)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 11:28
S171	608	(iso\$7 same nested) same (data or information or value) and (wafer or substrate or semiconductor or IC or workpiece)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 11:28
S172	1	US-20040185583-\$.DID.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 12:36
S173	182	(table same trim amount)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 12:57
S174	685	(table same trim (amount or value))	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 12:58
S175	2	"10890410"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:07
S176	4	"7291285"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:12
S177	0	"6858361" -	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:13

S178	10	"6858361"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:13
S179	3	table and trim (amount or value)	JPO	SAME	OFF	2010/11/03 13:21
S180	2493	(bin\$6 table)	JPO	SAME	OFF	2010/11/03 13:21
S181	19	(bin\$6 table) and wafer	JPO	SAME	OFF	2010/11/03 13:21
S182	16	(bin or binning table) and wafer	JPO	SAME	OFF	2010/11/03 13:22
S183	1	"10238453"	JPO	SAME	OFF	2010/11/03 13:24
S184	5	"10238453"	US-PGPUB; USPAT; JPO	SAME	OFF	2010/11/03 13:25
S185	0	"10464479"	JPO	SAME	OFF	2010/11/03 13:27
S186	1	"10464479"	US-PGPUB; USPAT; JPO	SAME	OFF	2010/11/03 13:27
S187	0	(700/110).ccls. and (table same (trim or strip) (amount or value)).clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:29
S188	61	(table same (trim or strip) same (amount or value)).clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:29
S189	1	(700/121).ccls. and (table same (trim or strip) (amount or value)).clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:29
S190	1	(700/121).ccls. and (table same (trim or etch or strip) (amount or value)).clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:30
S191	4259	(table same (trim or strip) same (amount or value))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:33
S192	11	(table same (trim or strip) same (amount or value)) and ((select\$3 or choos\$3) with recipe)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:33
S193	354	(438/8).ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:41
S194	91	(438/8).ccls. and (table)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:41
S195	25	(438/8).ccls. and (trim\$4 or cut\$4 or desired or traget or clip\$4 or retrim\$4) same (amount or value or quantity of total or partial or aberration)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:45

S196	20	(438/9).cls. and (trim\$4 or cut\$4 or desired or trajet or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:55
S197	5488	("438").clas. and (trim\$4 or cut\$4 or desired or trajet or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:57
S198	10351	("438").clas. and (trim\$4 or cut\$4 or desired or target or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:58
S199	5486	("438").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:58
S200	1384	("438").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration) and table	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:58
S201	79	("438").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration) and table and recipe	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 13:58
S202	63	("700").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration) and table and recipe	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 15:28
S203	184	(R2R or (run Run)) and recipe and (trim\$4 or strip \$4)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 15:30
S204	184	(R2R or (run run)) and recipe and (trim\$4 or strip \$4)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 15:30
S205	10	"7,209,798"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 15:37
S206	2	"20030020928"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 16:09

S207	8	"6665575"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 16:12
S208	5	"6864041"	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 16:12
S209	19	("216").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration) and table and recipe	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 16:23
S210	671	(430/316).cls.	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/03 17:50
S211	13	(430/316).cls. and nested	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2010/11/03 17:52
S212	3715	("430").clas. and (trim\$4 or cut\$4 or desired or traget or clip44 or retrim\$4) same (amount or value or quantity of total or partial or aberration)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 17:53
S213	9788	("430").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 17:53
S214	84	("430").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 17:53
S215	61	("430").clas. and (trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 17:54
S216	4058	(trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 18:00
S217	3747	(trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated and (recipe or process)	US-PGRUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 18:01

S218	2964	(trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated and (recipe or process) and (table or (Look up table))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	SAME	OFF	2010/11/03 18:01
S219	2964	(trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated and (recipe or process) and (table or (Look up table))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 18:01
S220	2964	(trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated and (recipe or process) and (table or (Look table))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 18:02
S221	1460	(trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated and (table or (Look table)) and ((select\$3 or choosi\$3 or determini\$3) with (recipe or process))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 18:03
S222	1460	(trim\$4 or cut\$4 or clip44 or retrim\$4 or etch\$3) same (amount or value or quantity of total or partial or aberration) and nested and isolated and (table or (Look table)) and ((select\$3 or choosi\$3 or determini\$3) with (recipe or process))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	ADJ	OFF	2010/11/03 18:03

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